

EXPRESS MAIL NO. EL 576 622 635 US

SAD  
#21  
1-22-01

DATE OF MAILING 6/16/60

Our Case No. 9651/4017  
Client Reference No. FTUS99005

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Hitoshi Seki et al.

Serial No.: To Be Assigned

Filing Date: Herewith 6-16-00

For Etching Reagent, And Method For  
Manufacturing Electronic Device  
Substrate And Electronic Device

)BEST AVAILABLE COPY

## **PRELIMINARY AMENDMENT**

**Assistant Commissioner for Patents  
Washington, D.C. 20231**

Dear Sir:

Prior to examination of the above-identified application, please amend the application as follows:

## In the Specification

~~On page 4, line 3 delete "a" and substitute --an--;~~

~~On page 4, line 17 delete "amount" and substitute --amounts--;~~

On page 5, line 18 delete "rapid etching rate" and substitute --rapidly etched--;

On page 5, line 22 delete "that" and substitute --and--;

On page 9, line 6 delete "Since the" and substitute --The--;

On page 27, line 7 delete "an";

On page 27, line 7 after "rate" ~~insert~~ --as--;

**On page 28, line 24 delete "an";**

On page 28, last line delete "by" and substitute --in--; and

On page 46, line 5 delete "yesy piece" and substitute --test piece--.